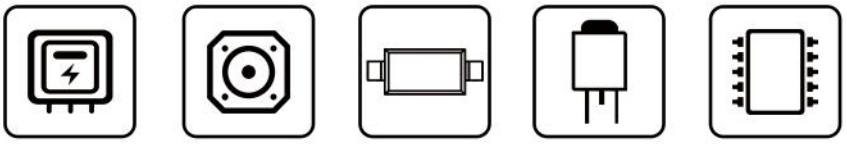
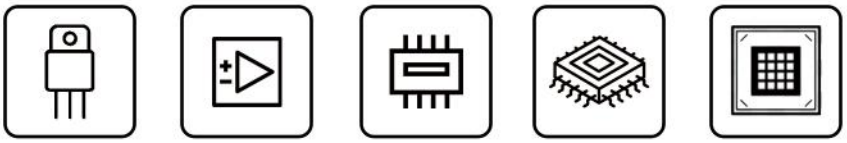
TDSEMIC
拓電半導體

自主封測 品質把控 售後保障

WEB | WWW.TDSEMIC.COM





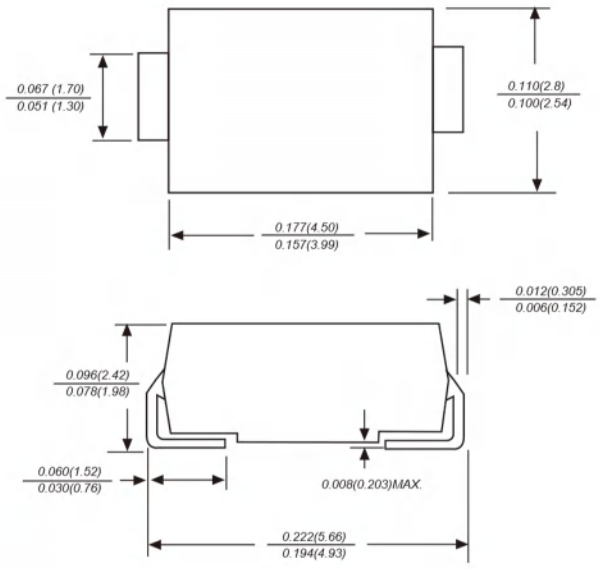
SS24

產品規格說明書

TDSEMIC

SS24 THRU SS2200

SMA/**DO-214AC**



Dimensions in inches and (millimeters)

FEATURES

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Metal silicon junction,majority carrier conduction
- Low power loss,high efficiency
- Built-in strain relief,ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 260°C/10 seconds at terminals

MECHANICAL DATA

Case: JEDEC DO-214AC molded plastic body
Terminals: leads solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight:0.002 ounce, 0.07 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

	SYMBOLS	SS22	SS23	SS24	SS25	SS26	SS28	SS210	SS2150	SS2200	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	150	200	VOLTS
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	105	140	VOLTS
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	150	200	VOLTS
Maximum average forward rectified current at T_L(see fig.1)	$I_{(AV)}$	2.0									Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50.0									Amps
Maximum instantaneous forward voltage at 2.0A	V_F	0.55			0.70		0.85			0.95	Volts
Maximum DC reverse current T_A=25°C	I_R	0.5							0.2		mA
at rated DC blocking voltage T_A=100°C		10.0					5.0		2.0		
Typical junction capacitance (NOTE 1)	C_J	220			180						pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	75.0									°C/W
Operating junction temperature range	T_J,	-65 to +125					-65 to +150				°C
Storage temperature range	T_{STG}	-65 to +150									°C

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2.P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

FIG. 1- FORWARD CURRENT DERATING CURVE

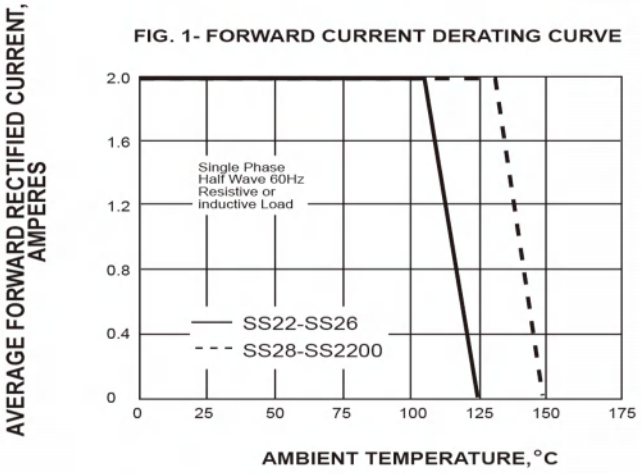


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

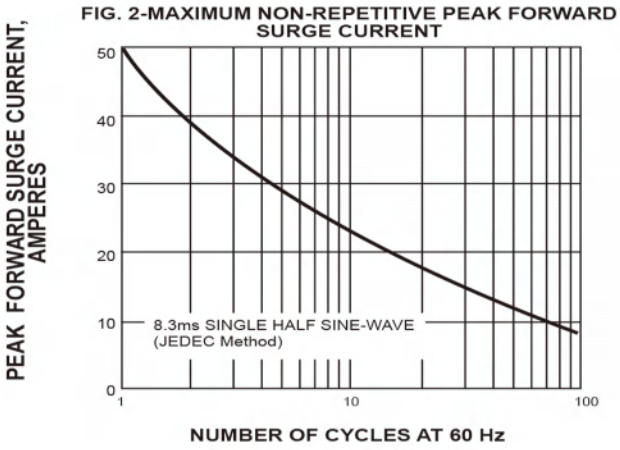


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

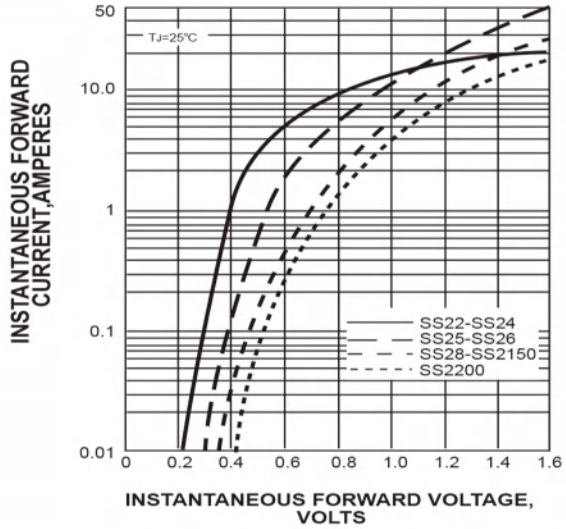


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

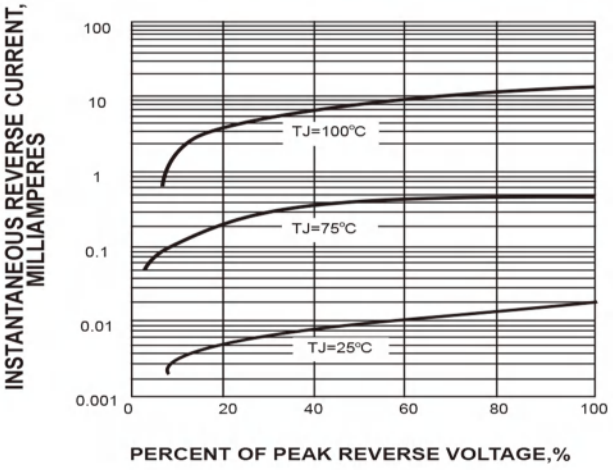


FIG. 5-TYPICAL JUNCTION CAPACITANCE

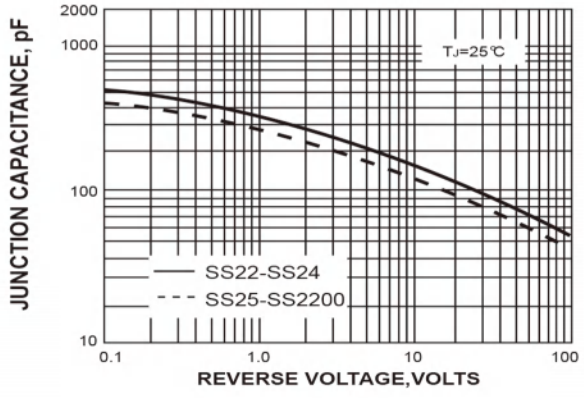


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE